3-1658013-1 ACTIVE

MICTOR

TE Internal #: 3-1658013-1

PCB Mount Header, Vertical, Board-to-Board, 28 Position, .8 mm [. 031 in] Centerline, Gold, Surface Mount, Power & Signal, Black

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical Connector System: Board-to-Board

Number of Positions: 28

Centerline (Pitch): .8 mm [.031 in]

Features

Product Type Features

| PCB Connector Assembly Type | PCB Mount Header |
|-----------------------------------|-----------------------|
| Connector System | Board-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features | |

Configuration Features

| Stackable | No |
|----------------------------------|-------------------|
| Connector Contact Load Condition | Differential Load |
| PCB Mount Orientation | Vertical |
| Number of Positions | 28 |
| Board-to-Board Configuration | Parallel |

Electrical Characteristics

| Dielectric Withstanding Voltage (Max) | 675 VAC |
|---------------------------------------|---------|
| Insulation Resistance | 2 ΜΩ |
| Impedance | 100 Ω |



| Operating Voltage | 125 VAC |
|---|------------------------------|
| Body Features | |
| Assembly Process Feature Material | Polyimide Film |
| Primary Product Color | Black |
| Contact Features | |
| PCB Contact Termination Area Plating Material Thickness | .25 μm[9.8425 μin] |
| Mating Tab Width | .38 mm[.015 in] |
| Mating Tab Width Mating Tab Thickness | .2 mm[.008 in] |
| Contact Shape & Form | Single Beam, Square |
| PCB Contact Termination Area Plating Material | Gold |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .25 μm[9.8425 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 1.25 A, 9.5 A |
| Termination Features | |
| Rectangular Termination Post & Tail Thickness | .2 mm[.008 in] |
| Rectangular Termination Post & Tail Width | .94 mm[.037 in] |
| Termination Method to Printed Circuit Board | Surface Mount |
| Mechanical Attachment | |
| PCB Mount Alignment Type | Locating Posts |
| Mating Retention | With |
| Mating Alignment | Without |
| PCB Mount Retention | With |
| PCB Mount Alignment | With |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | .8 mm[.031 in] |
| Housing Material | LCP (Liquid Crystal Polymer) |
| Dimensions | |
| Connector Height | 4.06 mm[.16 in] |
| Stack Height | 5 mm[.197 in] |
| | |



| PCB Thickness (Recommended) | .06 mm[.25 in] |
|-----------------------------|----------------------------|
| Usage Conditions | |
| Operating Temperature Range | -65 – 125 °C[-85 – 257 °F] |
| Operation/Application | |
| Assembly Process Feature | Pick and Place Cover |
| Circuit Application | Power & Signal |
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 96 |
| Packaging Type | Box, Tray |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



Compatible Parts



Customers Also Bought















Documents

Product Drawings

MSB0.80PL5ASY28DP,-,10,VCTY

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_3-1658013-1_K.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_3-1658013-1_K.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_3-1658013-1_K.3d_stp.zip

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English

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Datasheets & Catalog Pages

MICTOR SB CONNECTORS

English

Product Specifications

Application Specification

English